

Contents

Part I Overview and Fundamentals

1	Introduction	3
1.1	Conventional Laser Processing	4
1.2	Laser Chemical Processing	7
2	Thermal, Photophysical, and Photochemical Processes	13
2.1	Excitation Mechanisms, Relaxation Times	13
2.2	The Heat Equation	18
2.2.1	The Source Term	19
2.2.2	Dimensionality of Heat Flow	20
2.2.3	Kirchhoff and Crank Transforms	21
2.2.4	Phase Changes	22
2.2.5	Limits of Validity	23
2.3	Selective Excitations of Molecules	24
2.3.1	Electronic Excitations	25
2.3.2	Infrared Vibrational Excitations	28
2.4	Surface Excitations	34
2.4.1	External Photoeffect	34
2.4.2	Internal Photoeffect	34
2.4.3	Electromagnetic Field Enhancement, Catalytic Effects	36
2.4.4	Adsorbed Molecules	36
3	Reaction Kinetics and Transport of Species	39
3.1	Photothermal Reactions	41
3.2	Photochemical Reactions	43
3.3	The Concentration of Species	44
3.3.1	Basic Equations	45
3.3.2	Dependence of Coefficients on Temperature and Concentration	49
3.4	Heterogeneous Reactions	50
3.4.1	Stationary Equations	51
3.4.2	Transport Limitations	52
3.4.3	Dynamic Solutions	56
3.4.4	Heterogeneous Versus Homogeneous Activation	57

3.5	Combined Heterogeneous and Homogeneous Reactions	58
3.5.1	The Boundary-Value Problem	59
3.5.2	Approximate Solutions	60
3.6	Homogeneous Photochemical Activation	60
4	Nucleation and Cluster Formation	63
4.1	Homogeneous Processes	63
4.1.1	Classical Kinetics	64
4.1.2	Droplets Within a Laser Beam	66
4.1.3	Transport of Clusters, Thermophoresis, Chemophoresis	69
4.1.4	Cluster Formation by Pulsed-Laser Ablation	70
4.2	Heterogeneous Processes	73
4.2.1	Nucleation in LCVD	74
4.2.2	Condensation of Clusters from Vapor/Plasma Plumes	76
4.2.3	Cluster Formation Within Solid Surfaces	79
5	Lasers, Experimental Aspects, Spatial Confinement	81
5.1	Lasers	81
5.1.1	CW Lasers, Gaussian Beams	81
5.1.2	Pulsed and High-Power CW Lasers	83
5.2	Experimental Aspects	85
5.2.1	Microprocessing	86
5.2.2	The Reaction Chamber; Typical Setup	89
5.2.3	Large-Area Processing	90
5.2.4	Substrates	91
5.3	Confinement of the Excitation	92
5.3.1	The Thermal Field	92
5.3.2	Non-thermal Substrate Excitations	93
5.3.3	Gas-, Liquid- and Adsorbed-Phase Excitations	93
5.3.4	Plasma Formation	94
5.3.5	Material Damages	94
5.3.6	Non-linearities	94

Part II Temperature Distributions and Surface Melting

6	General Solutions of the Heat Equation	101
6.1	The Boundary-Value Problem	101
6.1.1	The Attenuation Function, $f(z)$	102
6.1.2	Boundary and Initial Conditions	103
6.2	Analytical Solutions	106
6.3	Pulse Shapes	108
6.4	Beam Shapes	111
6.5	Characteristics of Temperature Distributions	112
6.6	Numerical Techniques	114

7	Semi-infinite Substrates	117
7.1	The Center-Temperature Rise	117
7.2	Stationary Solutions for Temperature-Independent Parameters	118
7.2.1	Surface Absorption	119
7.2.2	Finite Absorption	121
7.3	Stationary Solutions for Temperature-Dependent Parameters	123
7.4	Scanned CW-Laser Beam	125
7.5	Pulsed-Laser Irradiation 7.5.1 Gaussian Intensity Profile	128
7.5.2	Uniform Irradiation	130
7.6	Dynamic Solutions for Temperature-Dependent Parameters	131
8	Infinite Slabs	137
8.1	Strong Absorption 8.1.1 Thermally Thin Film	137
8.1.2	Scanned CW Laser	138
8.2	The Influence of Interferences	140
8.3	Coupling of Optical and Thermal Properties	142
9	Non-uniform Media	145
9.1	Continuous Changes in Optical Properties	145
9.2	Absorption of Light in Multilayer Structures 9.2.1 Thin Films	147
9.2.2	Two-Layer Structures	149
9.2.3	Three-Layer Systems	149
9.3	Temperature Distributions for Large-Area Irradiation	150
9.3.1	Stationary Solutions for Thin Films	150
9.3.2	Dynamic Solutions	151
9.4	Temperature Distributions for Focused Irradiation	152
9.4.1	Strong Film Absorption	153
9.4.2	Finite Film Absorption	155
9.5	The Ambient Medium	157
9.5.1	Influence on Substrate Temperature	157
9.5.2	Indirect Heating	159
9.5.3	Free Convection	159
9.5.4	Temperature Jump	162
10	Surface Melting	165
10.1	Temperature Distributions, Interface Velocities 10.1.1 Boundary Conditions	165
10.1.2	Temperature Dependence of Parameters	168
10.2	Solidification	174
10.3	Process Optimization	176
10.4	Convection	177

10.5	Surface Deformations	179
10.6	Welding	180
10.7	Liquid-Phase Expulsion	182

Part III Material Removal

11	Vaporization, Plasma Formation	187
11.1	Energy Balance	189
11.2	One-Dimensional Model	189
11.2.1	Stationary Evaporation	193
11.2.2	Non-stationary Evaporation	197
11.2.3	Optimal Conditions	199
11.3	Knudsen Layer, the Recoil Pressure	200
11.4	Influence of a Liquid Layer	202
11.5	Limitations of Model Calculations	205
11.6	Plasma Formation	206
11.6.1	Ionization	207
11.6.2	Optical Properties of Plasmas	207
11.7	Laser-Supported Absorption Waves (LSAW)	212
11.7.1	Laser-Supported Combustion Waves (LSCW): $I_p \leq I \leq I_d$	212
11.7.2	Laser-Supported Detonation Waves (LSDW): $I \geq I_d$	214
11.7.3	Superdetonation	215
11.8	Abrasive Laser Machining	215
11.8.1	Cutting, Drilling, Shaping	216
11.8.2	Non-metals	218
11.8.3	Scribing, Marking, Engraving	218
11.8.4	Comparison of Techniques	219
12	Nanosecond-Laser Ablation	221
12.1	Surface Patterning	222
12.2	Ablation Mechanisms	226
12.2.1	Models	227
12.3	Photothermal Surface Ablation	231
12.4	Interactions Below Threshold	234
12.5	The Threshold Fluence, ϕ_{th}	236
12.6	Ablation Rates	240
12.6.1	Dependence on Photon Energy and Fluence	240
12.6.2	Dependence on Pulse Duration	242
12.6.3	Influence of Spot Size, Screening	242
12.6.4	Dependence on Pulse Number	244
12.6.5	Influence of an Ambient Atmosphere	246
12.7	Photothermal Volume Decomposition	247
12.8	Photochemical Ablation	249

12.8.1	Dissociation of Polymer Chains	250
12.8.2	Defect-Related Processes, Incubation	250
12.9	Thermo- and Photomechanical Ablation	252
12.9.1	Basic Equations	252
12.9.2	Biological Tissues	254
12.10	Material Damage, Debris	255
12.10.1	Strong Absorption	255
12.10.2	Finite Absorption	256
12.10.3	Debris	257
13	Ultrashort-Pulse Laser Ablation	259
13.1	Material Patterning and Damage	259
13.2	Photothermal Ablation	262
13.3	Photophysical Ablation	264
13.3.1	Long Pulses	265
13.3.2	Short Pulses	266
13.3.3	Time-Resolved Dynamics	266
13.3.4	Photophysical Versus Thermal Ablation	267
13.4	Molecular Dynamics (MD) Simulations	268
13.5	The Two-Temperature Model	270
13.5.1	Damage Thresholds	273
13.5.2	Ablation Rates	274
13.6	Avalanche- and Multiphoton Ionization	276
13.6.1	High-Aspect-Ratio Holes	277
13.6.2	Fabrication of Cavities in Bulk Materials	278
13.7	Ablation at Overcritical Temperatures	280
13.8	Comparison of Nanosecond and Ultrashort-Pulse Laser Ablation	281
14	Etching of Metals and Insulators	285
14.1	Photochemistry of Precursor Molecules	287
14.1.1	Halides	287
14.1.2	Halogen Compounds	288
14.2	Concentration of Reactive Species	290
14.2.1	Ballistic Approximation	291
14.2.2	Diffusion	292
14.2.3	Influence of the Reaction Chamber	293
14.2.4	Gas-Phase Recombination	295
14.2.5	Gas-Phase Heating	297
14.3	Dry-Etching of Metals	297
14.3.1	Spontaneous Etching Systems	297
14.3.2	Diffusive Etching Systems	297
14.3.3	Passivating Reaction Systems	300
14.4	Dry-Etching of Inorganic Insulators	301
14.4.1	SiO ₂ Glasses	301

14.4.2	Oxides	302
14.5	Wet-Etching	304
15	Etching of Semiconductors	307
15.1	Dark Etching	307
15.2	Laser-Induced Etching of Si in Cl ₂	310
15.2.1	Surface Patterning	310
15.2.2	Photochemical and Thermal Etching	311
15.2.3	Chlorine Radicals	313
15.2.4	Electron–Hole Pairs	314
15.2.5	Crystal Orientation and Doping	316
15.3	Si in Halogen Compounds	317
15.3.1	Si in XeF ₂	317
15.3.2	Si in SF ₆	318
15.4	Microscopic Mechanisms	320
15.5	Dry-Etching of Compound Semiconductors	321
15.5.1	III–V Compounds	322
15.5.2	Laser Etching of Atomic Layers	324
15.5.3	Dopants, Impurities, and Defects	324
15.6	Wet-Etching	325
15.6.1	Silicon	325
15.6.2	Compound Semiconductors	326
15.6.3	Interpretation of Results	327
15.6.4	Spatial Resolution, Waveguiding	330

Part IV Material Deposition

16	Laser-CVD of Microstructures	337
16.1	Precursor Molecules	337
16.2	Pyrolytic LCVD of Spots	338
16.2.1	Deposition from Halides	338
16.2.2	Deposition from Carbonyls	343
16.3	Modelling of Pyrolytic LCVD	343
16.3.1	Gas-Phase Processes	344
16.3.2	The Coupling Between $T(\mathbf{x})$ and $h(\mathbf{x})$	347
16.4	Temperature Distributions on Circular Deposits	349
16.5	Simulation of Pyrolytic Growth	353
16.6	Photolytic LCVD	356
16.6.1	Metals	357
16.6.2	Other Materials	359
16.6.3	Process Limitations	359

17 Growth of Fibers	361
17.1 In Situ Temperature Measurements	362
17.2 Microstructure and Physical Properties	363
17.3 Kinetic Studies	365
17.4 Gas-Phase Transport	367
17.4.1 The Coupling of Fluxes	367
17.4.2 Thermal Diffusion (Soret Effect)	369
17.5 Simulation of Growth	372
18 Direct Writing	375
18.1 Characteristics of Pyrolytic Direct Writing	375
18.1.1 Dependence on Laser Parameters and Substrate Material	376
18.1.2 Electrical Properties	378
18.2 Temperature Distributions in Direct Writing	379
18.2.1 Center-Temperature Rise	379
18.2.2 1D Approach, $\kappa^* \gg 1$	381
18.2.3 Numerical Solutions	382
18.3 Simulation of Direct Writing	383
18.3.1 1D Model	383
18.3.2 Comparison with Experimental Data	385
18.3.3 2D Model	388
18.4 Photophysical LCVD	389
18.5 Applications of LCVD in Microfabrication	391
18.5.1 Planar Substrates	392
18.5.2 Non-planar Substrates, 3D Objects	393
19 Thin-Film Formation by Laser-CVD	397
19.1 Direct Heating	398
19.1.1 Stationary Solutions	398
19.1.2 Non-stationary Solutions	401
19.2 Pyrolytic Processing Rates	402
19.2.1 Diffusion	403
19.2.2 Recombination	404
19.3 Photolytic Processing Rates	405
19.4 Metals	406
19.4.1 Deposition from Metal Halides	406
19.4.2 Deposition from Alkyls and Carbonyls	409
19.5 Semiconductors	410
19.5.1 Photodecomposition of Silanes	410
19.5.2 Crystalline Ge and Si	412
19.5.3 Amorphous Hydrogenated Silicon (a-Si:H)	413
19.5.4 Compound Semiconductors	417
19.5.5 Carbon	420
19.6 Insulators	420

19.6.1	Oxides	420
19.6.2	Nitrides	424
19.7	Heterostructures	426
19.8	Comparison of LCVD and Standard Techniques	427
20	Adsorbed Layers, Laser-MBE	429
20.1	Fundamental Aspects	430
20.2	Deposition from Adsorbed Layers	434
20.2.1	Vacuum	435
20.2.2	Gaseous Ambient	437
20.3	Combined Laser and Molecular/Atomic Beams	442
20.3.1	Laser-MBE	442
20.3.2	Laser-ALE	444
20.3.3	Laser-OMBD	446
20.3.4	Laser-Focused Atomic Deposition	447
21	Liquid-Phase Deposition, Electroplating	449
21.1	Liquid-Phase Processing Without an External EMF	449
21.1.1	Thermal Decomposition	449
21.1.2	Electroless Plating	452
21.1.3	Metal-Liquid Interfaces	452
21.1.4	Semiconductor-Liquid Interfaces	454
21.1.5	Further Experimental Examples	455
21.2	Electrochemical Plating	455
22	Thin-Film Formation by Pulsed-Laser Deposition and Laser-Induced Evaporation	459
22.1	Experimental Requirements	460
22.1.1	Congruent and Incongruent Ablation	463
22.1.2	Targets	464
22.2	Volume and Surface Processes, Film Growth	467
22.2.1	Plasma and Gas-Phase Reactions	467
22.2.2	Substrate Temperature, Laser-Pulse-Repetition Rate	469
22.2.3	Energetic Species	470
22.2.4	Particulates	470
22.2.5	Chemical Composition and Thickness of Films	474
22.3	Overview of Materials and Film Properties	475
22.4	High-Temperature Superconductors	476
22.4.1	Non-reactive Deposition	476
22.4.2	Reactive Deposition	477
22.4.3	Heterostructures	481
22.4.4	Metastable Compounds, Mixed Systems	481
22.4.5	Films with Step-like Morphology	482
22.5	Metals, Semiconductors, and Insulators	484
22.5.1	Element Semiconductors	484

22.5.2	Compound Semiconductors	484
22.5.3	Carbon Films	486
22.5.4	Dielectric Materials	487
22.5.5	Ferroelectric Materials	487
22.5.6	Magnetic Films	489
22.6	Nanocrystalline Films	489
22.7	Organic Materials	491
22.8	Laser-Induced Forward Transfer	493

Part V Material Transformations, Synthesis and Structure Formation

23	Structural Transformations, Laser Cleaning	499
23.1	Transformation Hardening	499
23.2	Laser Annealing, Recrystallization	501
23.2.1	Ion-Implanted Semiconductors	501
23.2.2	Thin Films	504
23.3	Glazing	504
23.4	Shock Hardening	505
23.5	Laser Polishing	505
23.6	Transformations Within Bulk Materials	507
23.7	Laser Cleaning	509
23.7.1	Dry Cleaning	512
23.7.2	Steam Cleaning	515
24	Doping	517
24.1	Solid-Phase Diffusion	517
24.2	Liquid-Phase Transport	520
24.3	Sheet Doping	521
24.3.1	Silicon	521
24.3.2	Compound Semiconductors	524
24.4	Local Doping	525
24.5	Laser Implantation	526
25	Cladding, Alloying, and Synthesis	527
25.1	Laser-Assisted Cladding and Sintering	527
25.2	Alloying	528
25.2.1	Laser-Surface Alloying	529
25.2.2	Formation of Metastable Materials	529
25.2.3	Silicides	530
25.3	Synthesis	531
25.3.1	Thin Films	531
25.3.2	Fibers	532

26 Oxidation, Nitridation, and Reduction	535
26.1 Basic Mechanisms	536
26.2 Metals	541
26.2.1 Photothermal Oxidation	541
26.2.2 Photochemical Contributions	543
26.2.3 Oxidation by Pulsed-Laser Plasma Chemistry	544
26.2.4 Nitridation	544
26.3 Elemental Semiconductors	545
26.3.1 Photothermal Oxidation of Si	545
26.3.2 Photochemically Enhanced Oxidation of Si	547
26.3.3 Nitridation of Silicon	548
26.4 Compound Semiconductors	549
26.5 Oxide Transformation, Reoxidation	550
26.6 Reduction and Metallization of Oxides	551
26.6.1 Qualitative Description	551
26.6.2 Oxidic Perovskites and Related Materials	553
26.6.3 Superconductors	555
27 Transformation and Decomposition of Organic Materials	557
27.1 Surface Modification of Polymers	557
27.1.1 Laser-Enhanced Adhesion	557
27.1.2 Swelling, Amorphization, Crystallization	559
27.1.3 Photochemical Exchange of Species	560
27.1.4 Chemical Degradation	561
27.2 Chemical Transformations Within Thin Films and Bulk Materials	562
27.2.1 Laser Lithography	563
27.2.2 Decomposition of Precursor Films	568
27.3 Laser-LIGA	570
28 Instabilities and Structure Formation	571
28.1 Coherent and Non-coherent Structures	571
28.2 Ripple Formation	574
28.2.1 Interference Pattern	575
28.2.2 Distribution of Energy	579
28.2.3 Feedback	581
28.2.4 Comparison of Experimental and Theoretical Results	582
28.3 Spatio-temporal Oscillations	586
28.3.1 Zero Isoclines	587
28.3.2 Instabilities in Laser-Induced Oxidation	588
28.3.3 Explosive Crystallization	589
28.3.4 Exothermal Reactions	591
28.3.5 Instabilities in Direct Writing	591
28.3.6 Discontinuous Deposition and Bistabilities	595

28.4	Instabilities in Laser Ablation	598
28.5	Hydrodynamic Instabilities	605
28.6	Stress-Related Instabilities	611
28.7	Technological Aspects	614

Part VI Measurement Techniques, Diagnostics

29	Measurement Techniques	619
29.1	Characterization of Laser-Beam Profiles	619
29.2	Homogenization of Laser Beams	619
29.3	Deposition, Etch, and Ablation Rates	621
29.4	Temperature Measurements	624
29.4.1	Photoelectric Pyrometry	625
29.4.2	Other Optical Techniques	627
29.4.3	Other Techniques	629
30	Analysis of Species, Plasmas, and Surfaces	631
30.1	Precursor and Product Species	631
30.1.1	Optical Spectroscopy	631
30.1.2	Mass Spectrometry	632
30.1.3	MALDI	634
30.2	Species in Vapor and Plasma Plumes	635
30.2.1	Species at Subthreshold Fluences	635
30.2.2	Atomic and Molecular Neutrals	635
30.2.3	Ions	637
30.2.4	Electrons, X-rays	637
30.2.5	Fragments and Clusters in Polymer Ablation	637
30.3	Plume Expansion, Shock Waves	638
30.3.1	Expansion in a Vacuum	638
30.3.2	Propagation in Gases	640
30.3.3	Propagation in Liquids	647
30.4	Processed Surfaces and Thin Films	649
30.4.1	Optical Techniques	650
30.4.2	Other Techniques	650
30.4.3	Transport Measurements	650

Appendices

A	Definitions and Formulas	655
A.1	Symbols and Conversion Factors	655
A.2	Abbreviations, Acronyms	661
A.3	Mathematical Functions and Relations	664
A.3.1	Bessel Function	664

A.3.2	Error Function	665
A.3.3	Exponential Integral Function	666
A.3.4	Gamma Function	666
A.3.5	Heaviside Function	666
A.3.6	Jacobian Theta Function	666
A.4	The \mathcal{F} -Function	667
A.4.1	Axial Temperature Distribution for Infinite Slabs	667
A.4.2	Axial Temperature Distribution for Semi-infinite Substrates	668
B	Tabular Presentation of the Materials Investigated	671
B.1	Ablation of Inorganic Materials	671
B.2	Ablation of Organic Polymers	673
B.3	Materials Etching	674
B.4	LCVD of Microstructures	676
B.5	Thin-Film Formation by LCVD	677
B.6	Deposition From Adsorbed Layers and Atomic/Molecular Beams	679
B.7	Deposition from Liquids	680
B.8	Formation of Thin Films and Heterostructures by PLD	680
B.9	Laser Cleaning of Substrates from Particulates	687
B.10	Surface Oxidation, Nitridation, and Reduction	687
B.11	Transformation and Decomposition of Organic Materials, Laser Lithography	688
B.12	Biological and Medical Applications	689
C	Tables	691
References		713
Index		779